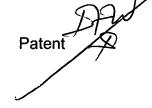
Attorney Docket No.: 111079-135918

IPN P14927X (Intel Corporation)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application of:

Boggs et al.

Application No.: 10/750,560

Filed: December 31, 2003

For: Electronic Substrate with Direct

Inner Layer Component

Interconnection

Mail Stop Amendment Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450 Examiner: Ishwarbhai B. Patel

Art Unit: 2841

Confirmation No. 5692

CERTIFICATE OF TRANSMISSION/MAILING

I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date shown below:

Typed or Printed: Heather LAdamson

RESPONSE TO OFFICE ACTION INTRODUCTORY COMMENTS

Dear Sir:

This communication is submitted in response to the Office Action mailed March 10, 2005 (herein "Office Action"). Applicants respectfully request reconsideration of the captioned application in view of the amendments and remarks to follow.

Amendments to the Claims are reflected in the listing of claims that begin on page 2 of this paper.

Amendendment to the Abstract begin on page 7 of this paper.

Remarks/Arguments begin on page 8 of this paper.